

General Features

• $V_{DS} = 60V, I_D = 0.115A$

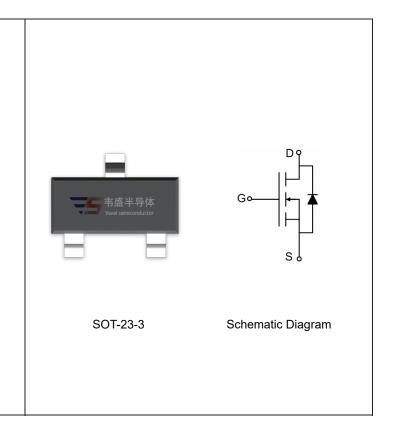
 $R_{DS(ON)} < 3.5\Omega$ @ $V_{GS}=5V$

 $R_{DS(ON)} < 3\Omega @ V_{GS}=10V$

- Lead free product is acquired
- Surface mount package

Application

- Direct logic-level interface: TTL/CMOS
- Drivers: relays, solenoids, lamps, hammers, display, memories, transistors, etc.
- Battery operated systems
- Solid-state relays



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM2N7002A-S2	VSM2N7002A	SOT-23-3	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _G S	±20	V
Drain Current-Continuous@ Current-Pulsed (Note 1)	I _D	0.115	Α
Drain Current-Continuous@ Current-Pulsed	I _{DM}	0.8	Α
Maximum Power Dissipation	P _D	0.2	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}\mathbb{C}$

Thermal Characteristic

Thermal Resistance,Junction-to-Ambient (Note 2)	R _{θJA}	625	°C/W
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Electrical Characteristics (TC=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	68	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μΑ	



Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA		
On Characteristics (Note 3)								
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	1	1.7	2.5	V		
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =5V, I _D =0.05A	-	2.3	3.5	Ω		
Diam-Source Off-State Resistance		V _{GS} =10V, I _D =0.5A	-	2.1	3	Ω		
Forward Transconductance	g FS	V _{DS} =10V,I _D =0.2A	0.08	-	-	S		
Dynamic Characteristics (Note4)								
Input Capacitance	C _{lss}	V _{DS} =30V,V _{GS} =0V,	-	20	50	PF		
Output Capacitance	Coss	F=1.0MHz	-	10	20	PF		
Reverse Transfer Capacitance	C _{rss}	F-1.0WHZ	-	3.6	5	PF		
Switching Characteristics (Note 4)								
Turn-on Delay Time	t _{d(on)}		-	10	-	nS		
Turn-on Rise Time	t _r	V_{DD} =30V, I_{D} =0.2A	-	50	-	nS		
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{GEN} =10 Ω	-	17	-	nS		
Turn-Off Fall Time	t _f		-	10	-	nS		
Total Gate Charge	Qg	V _{DS} =10V,I _D =0.115A,	_	1.7	3	nC		
Total Gate Charge		V _{GS} =4.5V	-					
Drain-Source Diode Characteristics								
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =0.115A	-	-	1.2	V		
Diode Forward Current (Note 2)	Is		-	-	0.115	Α		

Notes:

- $\textbf{1.} \ \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature.}$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

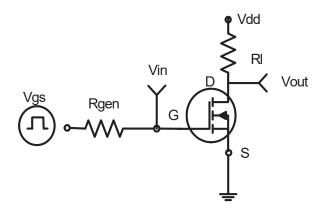


Figure 1:Switching Test Circuit

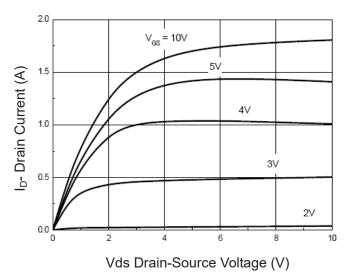


Figure 3 Output Characteristics

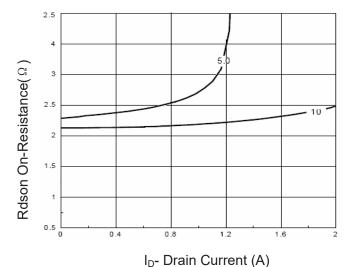


Figure 5 Drain-Source On-Resistance

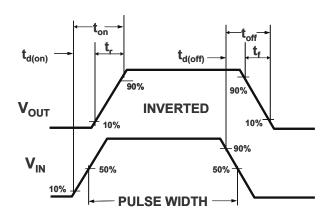


Figure 2:Switching Waveforms

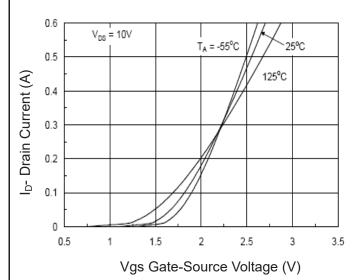


Figure 4 Transfer Characteristics

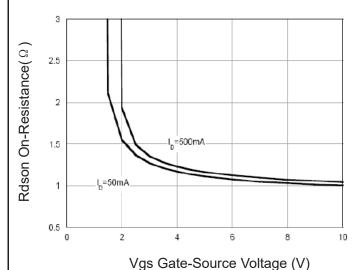
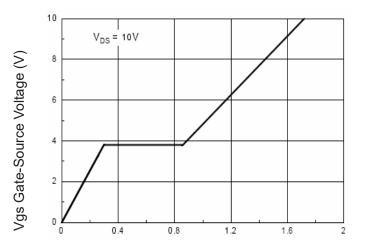


Figure 6 Rdson vs Vgs





Qg Gate Charge (nC) Figure 7 Gate Charge

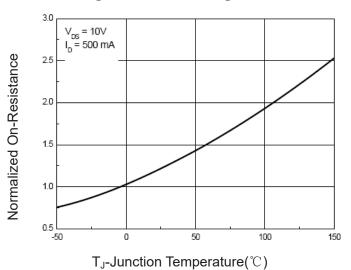


Figure 9 Drain-Source On-Resistance

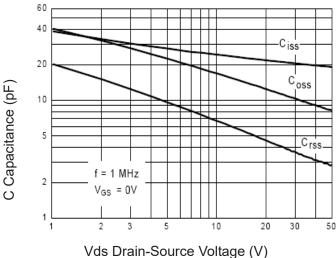
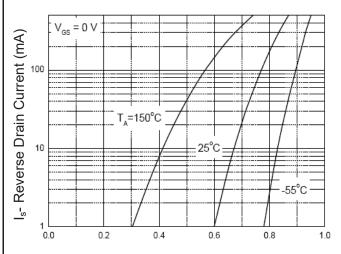
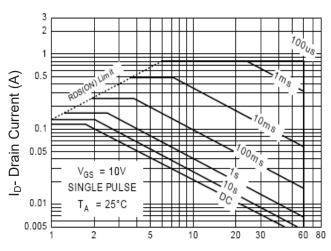


Figure 11 Capacitance vs Vds



Vsd Source-Drain Voltage (V)

Figure 8 Source-DrainDiode Forward



Vds Drain-Source Voltage (V)

Figure 10 Safe Operation Area



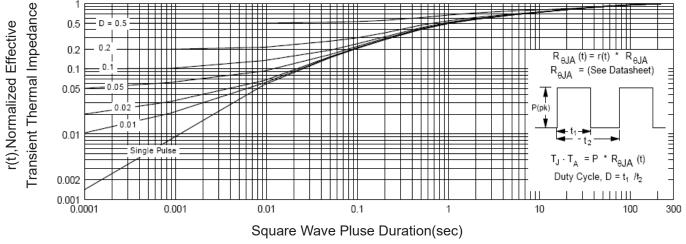


Figure 12 Normalized Maximum Transient Thermal Impedance